

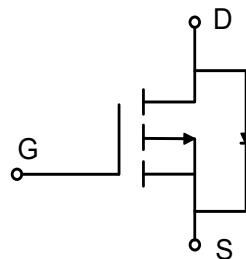
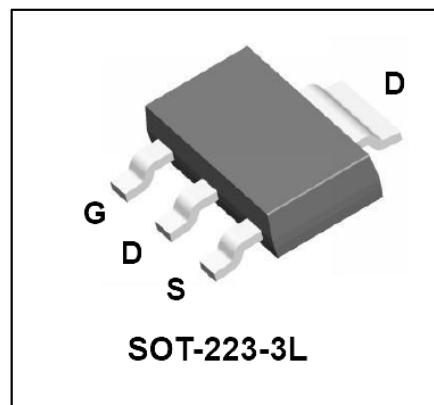
## 60V P-Channel Enhancement Mode Power MOSFET

**Description**

WMT04P06TS uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

**Features**

- $V_{DS} = -60V$ ,  $I_D = -3.8A$   
 $R_{DS(on)} < 115m\Omega$  @  $V_{GS} = -10V$   
 $R_{DS(on)} < 135m\Omega$  @  $V_{GS} = -4.5V$
- High Density Cell Design for Ultra Low Rdson
- Fully Characterized Avalanche Voltage and Current
- Excellent Package for Good Heat Dissipation

**Applications**

- DC/DC Converter
- LED Backlighting
- Motor Control

**Absolute Maximum Ratings ( $T_A = 25^\circ C$ , unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <small><math>T_A=25^\circ C</math></small>	$I_D$	-3.8	A
		-2.4	
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	-15.2	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	9.8	mJ
Total Power Dissipation	$P_D$	2.7	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	$R_{\theta JA}$	46.3	°C/W

**Electrical Characteristics ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = -250\mu\text{A}$	-60	-	-	V
Gate-body Leakage current	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current  $T_J=25^\circ\text{C}$	$I_{DSS}$	$V_{DS} = -60V, V_{GS} = 0V$	-	-	-1	$\mu\text{A}$
$T_J=100^\circ\text{C}$			-	-	-100	$\mu\text{A}$
Gate-Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1	-1.6	-2.5	V
Drain-Source On-Resistance <sup>4</sup>	$R_{DS(\text{on})}$	$V_{GS} = -10V, I_D = -2A$	-	85	115	$\text{m}\Omega$
		$V_{GS} = -4.5V, I_D = -1A$	-	90	135	
Forward Transconductance <sup>4</sup>	$g_{fs}$	$V_{DS} = -10V, I_D = -2A$	-	6	-	S
<b>Dynamic Characteristics<sup>5</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -30V, V_{GS} = 0V, f = 1\text{MHz}$	-	995	-	$\text{pF}$
Output Capacitance	$C_{oss}$		-	59	-	
Reverse Transfer Capacitance	$C_{rss}$		-	38	-	
Gate Resistance	$R_g$	$f = 1\text{MHz}$	-	11	-	$\Omega$
<b>Switching Characteristics<sup>5</sup></b>						
Total Gate Charge	$Q_g$	$V_{GS} = -10V, V_{DS} = -30V, I_D = -2A$	-	30	-	$\text{nC}$
Gate-Source Charge	$Q_{gs}$		-	4.7	-	
Gate-Drain Charge	$Q_{gd}$		-	3.8	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = -10V, V_{DD} = -30V, R_G = 3\Omega, I_D = -2A$	-	28	-	$\text{ns}$
Rise Time	$t_r$		-	66	-	
Turn-Off Delay Time	$t_{d(off)}$		-	9.8	-	
Fall Time	$t_f$		-	6.5	-	
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{SD}$	$I_S = -2A, V_{GS} = 0V$	-	-	-1.2	V
Continuous Source Current	$T_A = 25^\circ\text{C}$	$I_S$	-	-	-3.8	A

Note :

1. Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$ .
2. The EAS data shows Max. rating . The test condition is  $V_{DD} = -25V, V_{GS} = -10V, L = 0.4\text{mH}, I_{AS} = -7A$ .
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
5. This value is guaranteed by design hence it is not included in the production test.

## Typical Characteristics

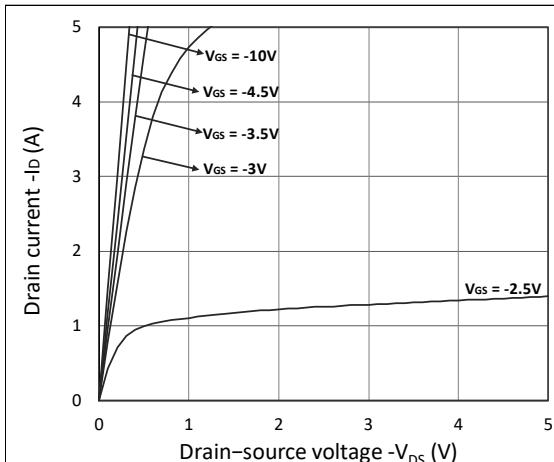


Figure 1. Output Characteristics

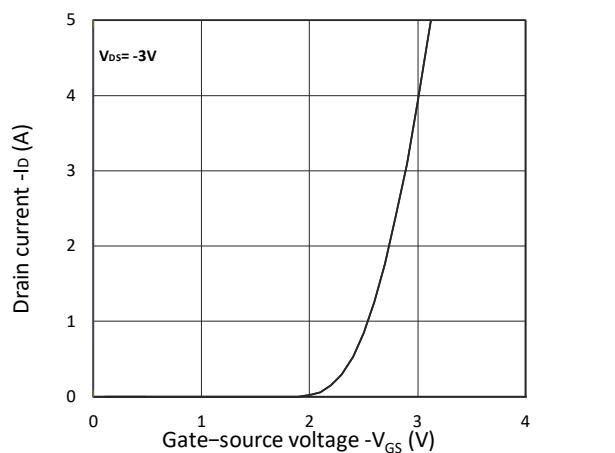


Figure 2. Transfer Characteristics

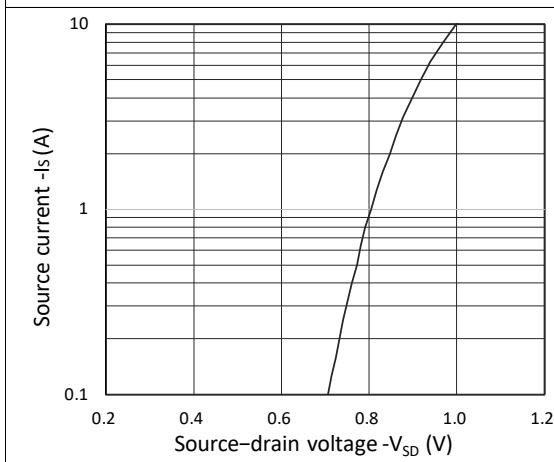
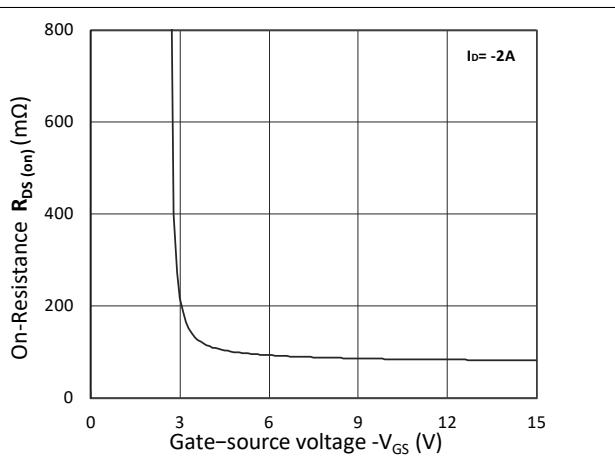
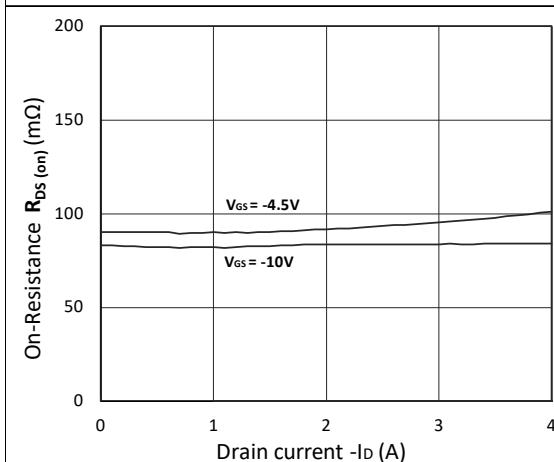
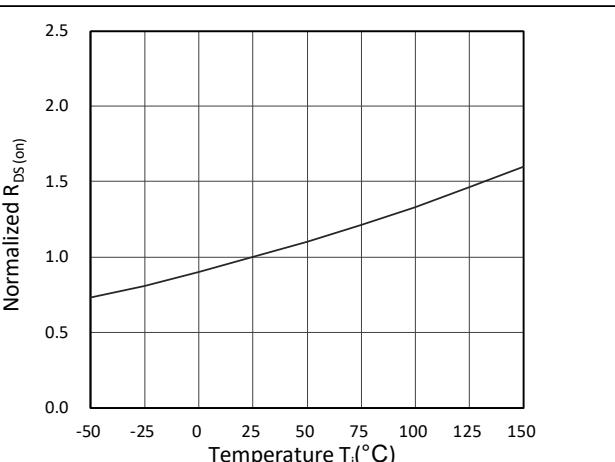


Figure 3. Forward Characteristics of Reverse

Figure 4.  $R_{DS(ON)}$  vs.  $V_{GS}$ Figure 5.  $R_{DS(ON)}$  vs.  $I_D$ Figure 6. Normalized  $R_{DS(ON)}$  vs. Temperature

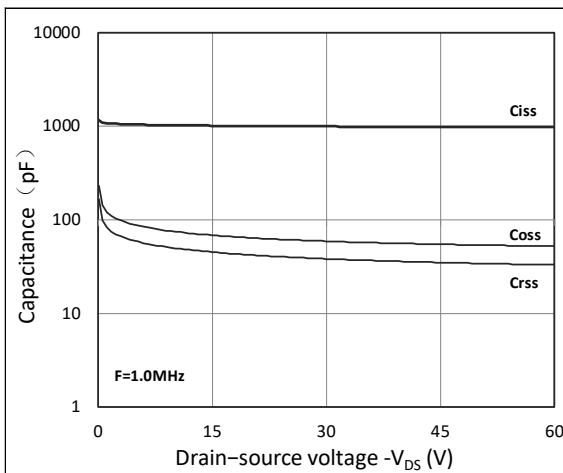


Figure 7. Capacitance Characteristics

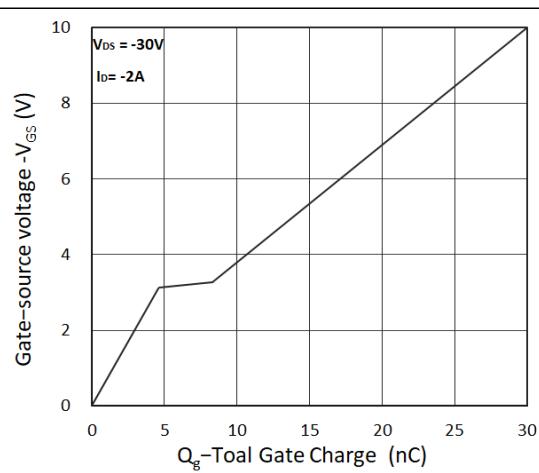


Figure 8. Gate Charge Characteristics

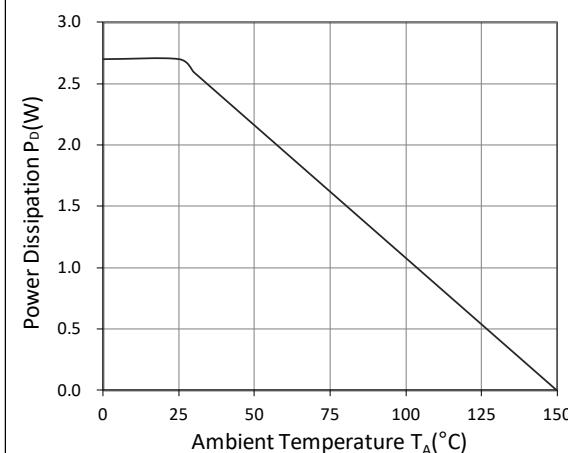


Figure 9. Power Dissipation

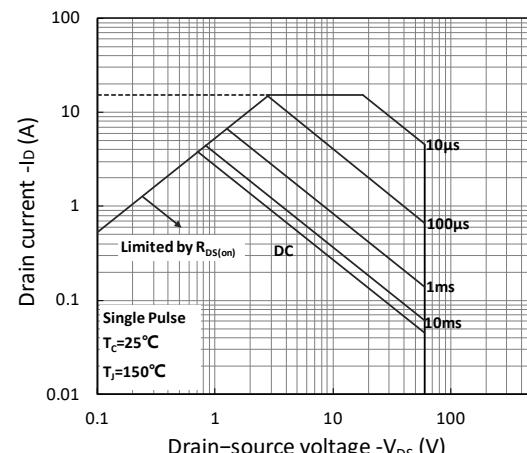


Figure 10. Safe Operating Area

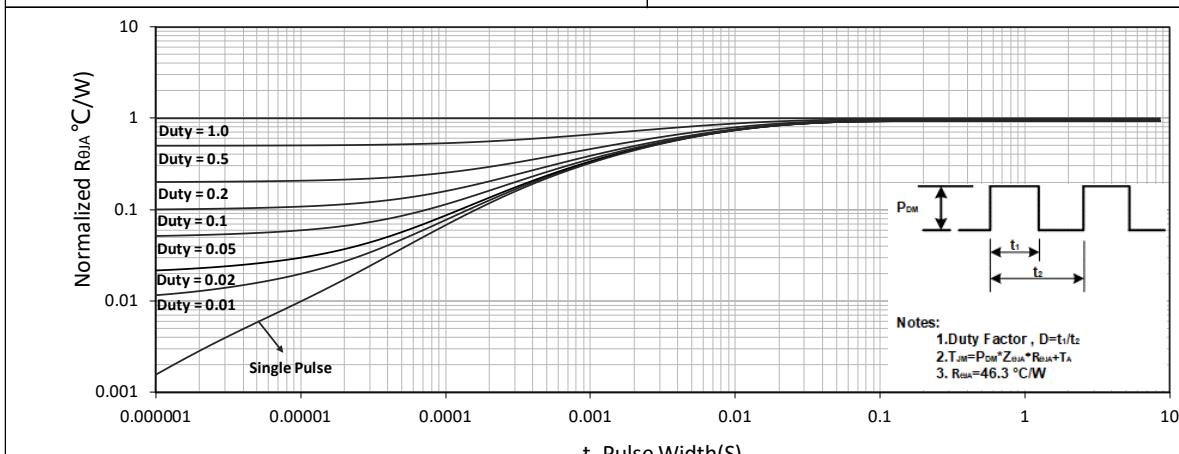
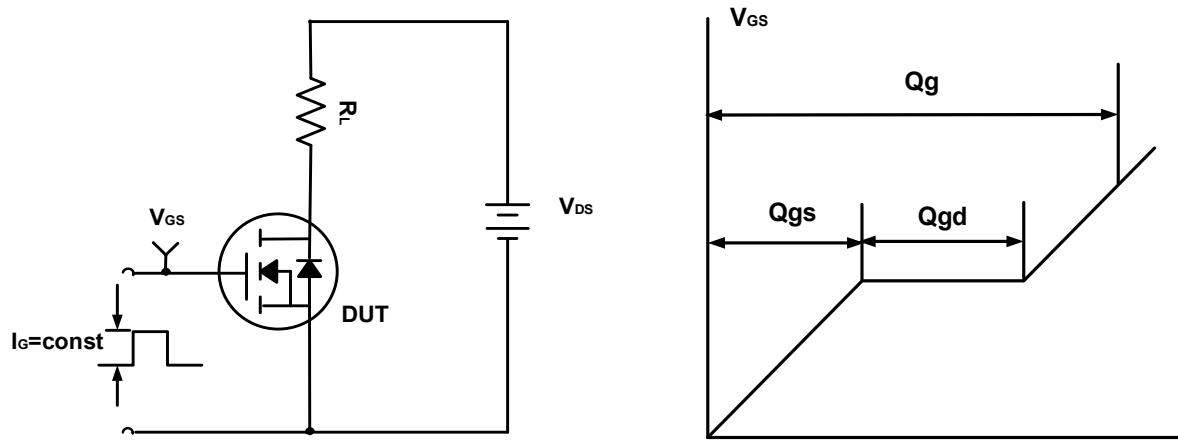
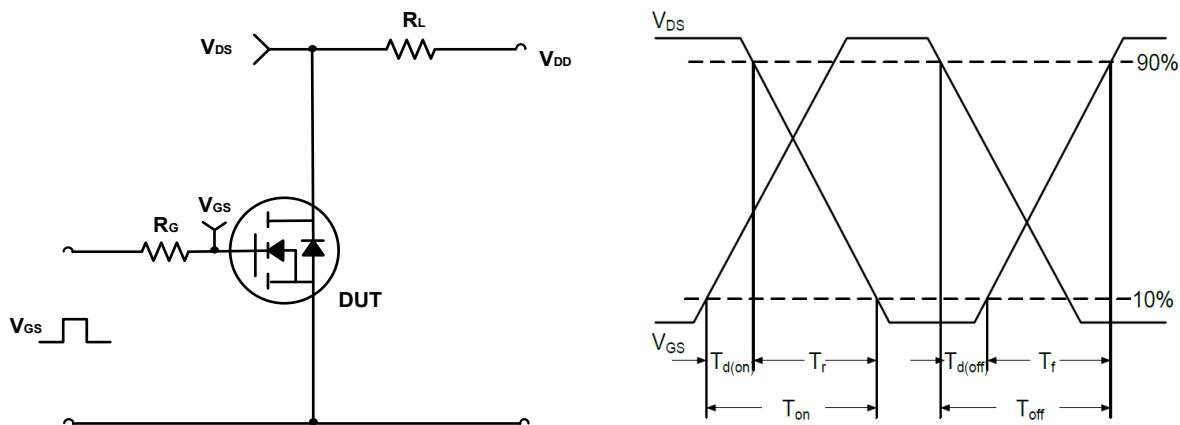
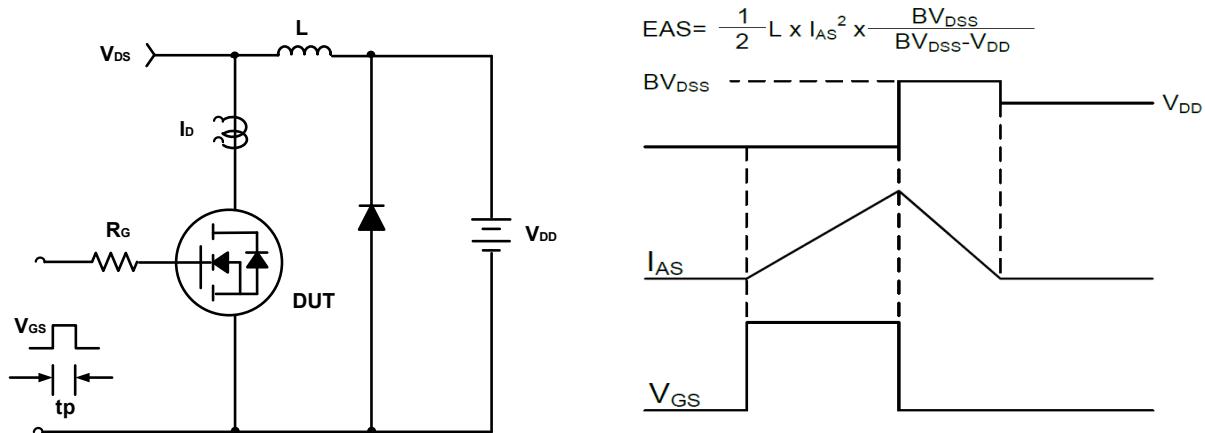
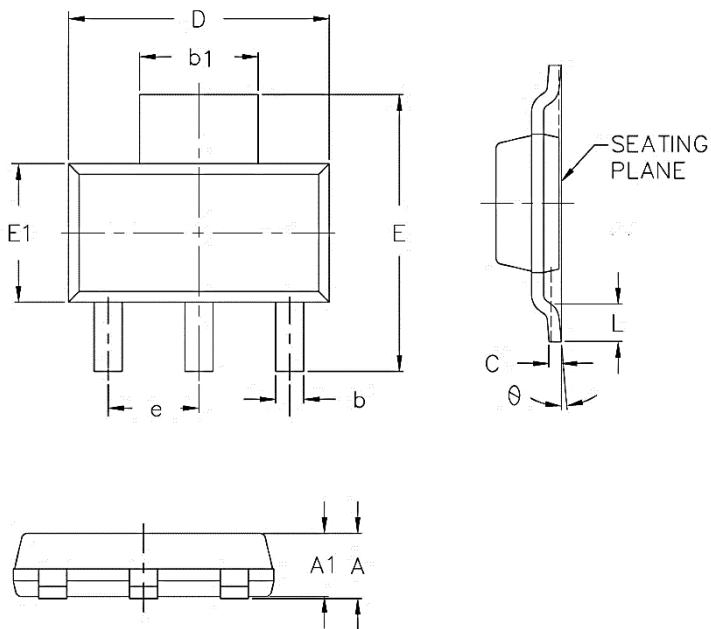


Figure 11. Normalized Maximum Transient Thermal Impedance

**Test Circuit****Figure A. Gate Charge Test Circuit & Waveforms****Figure B. Switching Test Circuit & Waveforms****Figure C. Unclamped Inductive Switching Circuit & Waveforms**

## Mechanical Dimensions for SOT-223-3L

## COMMON DIMENSIONS

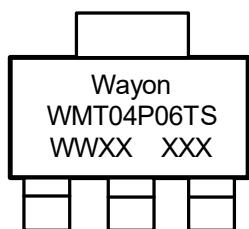


SYMBOL	MM	
	MIN	MAX
A	-	1.80
A1	1.45	1.75
b	0.60	0.84
b1	2.90	3.10
C	0.23	0.35
D	6.20	6.70
E	6.70	7.30
E1	3.30	3.70
e	2.30BSC	
L	0.80	-
$\theta$	$0^\circ$	$10^\circ$

## Ordering Information

Part	Package	Marking	Packing method
WMT04P06TS	SOT-223-3L	WMT04P06TS	Tape and Reel

## Marking Information



WMT04P06TS = Device code

WWXX XXX= Date code

## Contact Information

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